

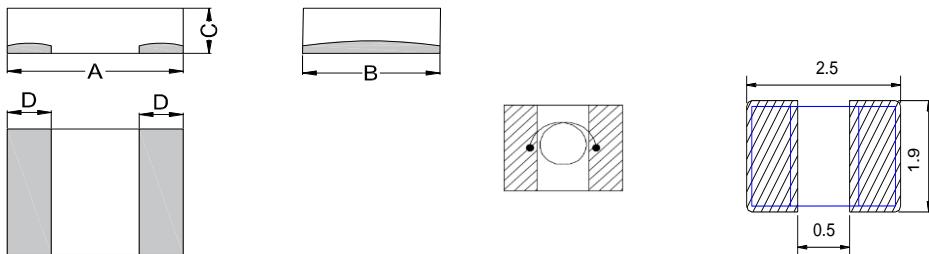


## ■ FEATURES

1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free and RoHS compliant.

## ■ DIMENSIONS (mm)

Recommended PC Board Pattern



Part No.	Size (mm)			
	A	B	C	D
SRIM 201610	2.00 ± 0.30	1.60 ± 0.30	0.80 ± 0.20	0.70 ± 0.30

## SERIES LIST

No.	Part No.	L ( $\mu$ H)	Test Freq. (Hz)	RDC (m $\Omega$ )		I sat (A)		I rms (A)	
				Typ.	Max.	Typ.	Max.	Typ.	Max.
1	SRIM 201610-R24M	0.24 $\pm$ 20%	100K/1V	18.0	20.5	7.7	6.7	6.5	5.5
2	SRIM 201610-R33M	0.33 $\pm$ 20%	100K/1V	21.0	26.0	7.0	6.2	5.7	5.2
3	SRIM 201610-R47M	0.47 $\pm$ 20%	100K/1V	28.0	32.0	6.0	5.3	5.3	4.7
4	SRIM 201610-R68M	0.68 $\pm$ 20%	100K/1V	44.0	50.0	5.0	4.4	4.0	3.4
5	SRIM 201610-1R0M	1.00 $\pm$ 20%	100K/1V	49.0	59.0	4.4	3.8	3.6	3.2
6	SRIM 201610-1R5M	1.50 $\pm$ 20%	100K/1V	80.0	96.0	3.0	2.7	2.6	2.3
7	SRIM 201610-2R2M	2.20 $\pm$ 20%	100K/1V	130.0	150.0	2.65	2.45	2.3	2.0

Note:

1. All test data referenced to 25°C ambient
2. Isat : Saturation Current (Isat) will cause L0 to drop approximately 30%.
3. Irms : Heat Rated Current (Irms) will cause the coil temperature rise approximately  $\Delta T$  of 40°C
4. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
5. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.  
Therefore temperature rise should be verified in application conditions.
6. Rated DC Current : The less value whith is Irms or Isat
7. Rated voltage 25V DC,The application of voltage depends on many factors , Over voltage may cause components failure , high temperature and burn-out,User needs to verify for appropriate usage.

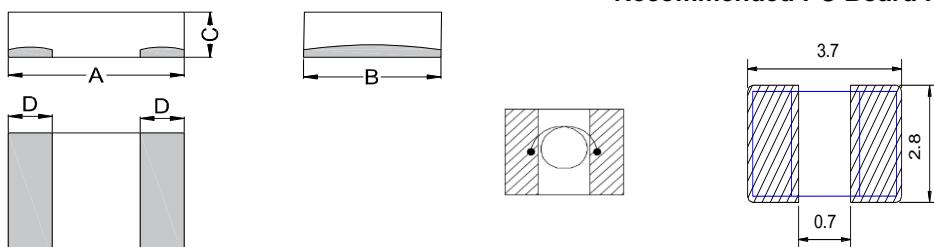


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## ■ DIMENSIONS (mm)

Recommended PC Board Pattern



Part No.	Size (mm)			
	A	B	C	D
SRIM 322510	3.20 ± 0.30	2.50 ± 0.30	0.80 ± 0.20	1.10 ± 0.30
SRIM 322512	3.20 ± 0.30	2.50 ± 0.30	1.00 ± 0.20	1.10 ± 0.30
SRIM 322520	3.20 ± 0.30	2.50 ± 0.30	1.80 ± 0.20	1.10 ± 0.30

## SERIES LIST

No.	Part No.	L ( $\mu$ H)	Test Freq. (Hz)	RDC (m $\Omega$ )	I sat (A)	I rms (A)
				Typ. Max.	Typ. Max.	Typ. Max.
1	SRIM 322510-R22M	0.22±20%	100K/1V	11.0 13.2	9.0 8.5	8.0 7.0
2	SRIM 322510-R33M	0.33±20%	100K/1V	15.0 18.0	8.0 7.0	7.0 6.0
3	SRIM 322510-R47M	0.47±20%	100K/1V	18.0 21.6	6.5 5.5	6.0 5.5
4	SRIM 322510-R68M	0.68±20%	100K/1V	22.0 26.4	6.0 5.2	5.5 5.0
5	SRIM 322510-1R0M	1.00±20%	100K/1V	30.0 36.0	4.8 4.0	4.8 4.0
6	SRIM 322510-1R5M	1.50±20%	100K/1V	48.3 58.0	4.3 3.8	3.8 3.2
7	SRIM 322510-2R2M	2.20±20%	100K/1V	67.0 80.4	3.6 3.3	3.1 2.7
8	SRIM 322510-3R3M	3.30±20%	100K/1V	100.0 120.0	3.1 2.8	2.5 2.1
9	SRIM 322510-4R7M	4.70±20%	100K/1V	143.0 172.0	2.2 1.9	2.0 1.7
1	SRIM 322512-R22M	0.22±20%	100K/1V	7.4 8.5	9.3 8.7	9.5 9.0
2	SRIM 322512-R33M	0.33±20%	100K/1V	10 13	9.1 8.5	8.5 8.0
3	SRIM 322512-R47M	0.47±20%	100K/1V	16 19.2	8.2 7.4	7.0 6.5
4	SRIM 322512-R68M	0.68±20%	100K/1V	20 24	7.3 6.8	6.2 5.7
5	SRIM 322512-1R0M	1.00±20%	100K/1V	26 32	6.5 5.7	5.5 5.0
6	SRIM 322512-1R5M	1.50±20%	100K/1V	44 53	5.0 4.5	4.4 3.9
7	SRIM 322512-2R2M	2.20±20%	100K/1V	61 73	4.8 4.3	4.0 3.6
8	SRIM 322512-3R3M	3.30±20%	100K/1V	87 101	3.4 3.0	3.1 2.8
9	SRIM 322512-4R7M	4.70±20%	100K/1V	122 146	2.8 2.4	2.2 1.9
1	SRIM 322520-R33M	0.33±20%	100K/1V	8.0 9.6	11.0 10.0	8.5 8.0
2	SRIM 322520-R47M	0.47±20%	100K/1V	9.3 11.2	9.0 8.0	8.0 7.5
3	SRIM 322520-R68M	0.68±20%	100K/1V	13.3 16.0	8.0 7.0	7.0 6.4
4	SRIM 322520-1R0M	1.00±20%	100K/1V	18.3 22.0	7.5 6.2	6.2 5.8
5	SRIM 322520-1R5M	1.50±20%	100K/1V	25.8 31.0	6.0 5.0	5.3 4.8
6	SRIM 322520-2R2M	2.2±20%	100K/1V	38.0 46.0	5.0 4.5	3.7 3.2
7	SRIM 322520-3R3M	3.3±20%	100K/1V	56.0 65.0	4.2 3.7	3.2 2.7
8	SRIM 322520-4R7M	4.7±20%	100K/1V	90.0 98.0	3.4 2.9	2.8 2.4

Note:

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